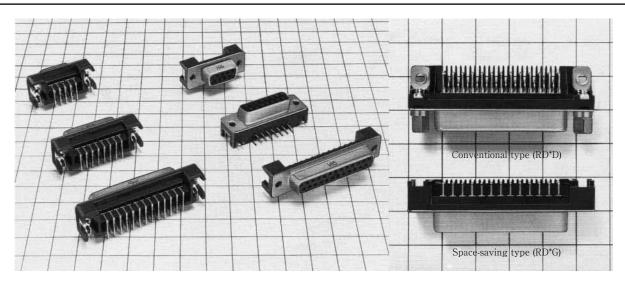
RD*G SERIES SPACE-SAVING D-SUBMINIATURE

General

The "RD*G" Series Right-angled D-Subminiature connectors are specially developed to answer the needs for smaller and lighter equipment such as personal computers peripherals and workstations.

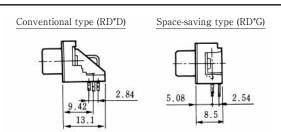
The PCB mounting section has been reduced in size while the mating section maintains the same configuration as the conventional models.

Female 9, 15 and 25 position sizes are available.



Features

- (1) 35% Space-saving is achieved in terms of depth and mounting area as compared to the conventional models (HIROSE's RD%D)
- (2) Weight is approximately 10% less than conventional models.
- (3) Full interchangeability in terms of mating with conventional D-Subminiature connectors. The mating section meets the international standard.
- (4) For smoother insertion and withdrawal, reliable partly gold-plated tulip-shaped contacts are used (same as the conventional models).
- (5) The lock pin grounding system which solders directly to the substrate eliminates troublesome hold down hardware.
- (6) Since they are fixed to the insulator (caulked), the metallic shells and lock pins do not become loose even when the lock screws are removed. This has improved assembly productivity of the units.



- (7) Two lock pin lengths for substrate thickness: t-1.2mm (0.05") and t-1.6mm (0.062") are available.
- (8) These are two Dip post lengths of 3.5mm and 2.8mm.
- (9) The new connectors are suitable for robotic insertion.
- (10) UL94V-0 insulator material offers excellent heat resistant and chemical resistant capability.
- (11) Metal shell structure offers improved grounding and EMI immunity.

Application

Electronic equipment such as personal computers, peripherals, workstations, measuring instruments, communications equipment, FA and control devices.

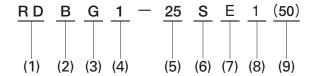
Electrical and Environmental

| Electrical performance | | | | |
|--|----------------------------|--|--|--|
| Current capacity | 3A | | | |
| Voltage rating | 350V AC | | | |
| Insulation resistance | 5,000 ohms min. at 500V DC | | | |
| Contact resistance | 25m ohms max at 100mA DC | | | |
| Withstanding voltage 1,250V AC r.m.s. for one minute | | | | |

Materials

| Materials | | | | |
|-----------|--------------|---|--|--|
| Shell | Copper | Nickel plating | | |
| Insulator | PBT | Black (UL94V-0) | | |
| Contact | Copper alloy | Nickel plating + selective gold plating | | |
| Lock pin | Copper alloy | Tin plating | | |

Ordering Informations



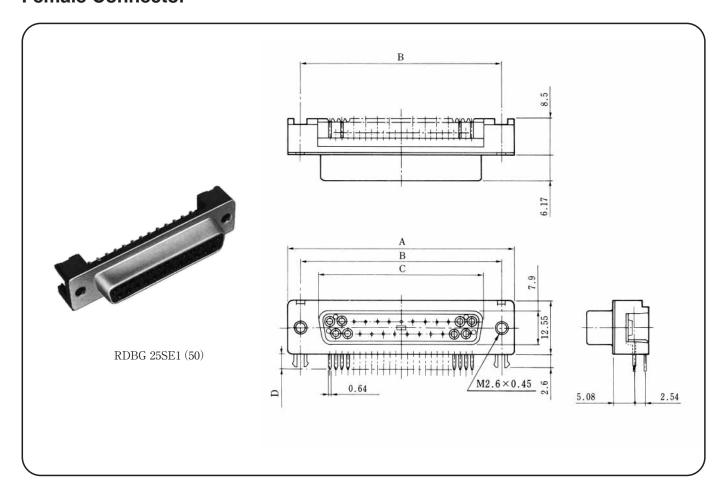
- (1) Series name: D Sub-right angled
- (2) Shell size: E (9), A (15), B (25)
- (3) Model type: G=Space saving type
- (4) Dip post length: Blank=3.5mm (.138")

1=2.8mm (.110")

- (5) No of contacts: 9, 15, 25
- (6) Connector style: S=Female
- (7) Mounting style: E=Grounding lock pin
- (8) Applicable board thickness: 1=(t1.6mm) 1.6mm (0.62"), 2=(t1.2mm) 1.2mm(0.50")
- (9) Specification contents(50): Nickel plating

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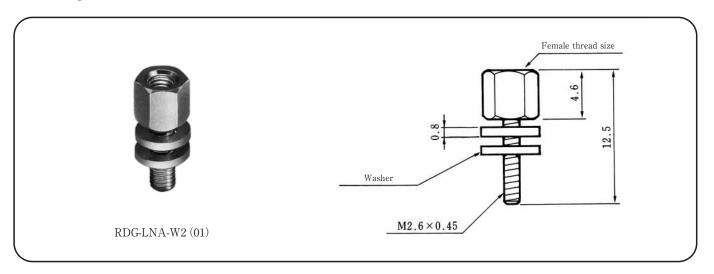
Female Connector



Unit: mm

| RoHS | Applicable substrate thickness | D | С | В | A | No. of Contacts | Part No. | HRS No | | | | | | | | | |
|------|-----------------------------------|-----|------------|---------|-------------|-----------------|------------------|------------------|-----------------|-------|-------|-------|-------|-------|----|------------------|-----------------|
| | 1.6 | | 16.34 | 24.99 | 30.81 | 9 | RDEG-9SE1 (50) | CL211-5200-7-50 | | | | | | | | | |
| | 1.2 | | 10.54 | 24.99 | 30.61 | 9 | RDEG-9SE2 (50) | CL211-5201-0-50 | | | | | | | | | |
| | 1.6 | 3.5 | 24.66 | 33.32 | 20.14 | 15 | RDAG-15SE1 (50) | CL211-5204-8-50 | | | | | | | | | |
| | 1.2 | 3.5 | 24.00 | 33.32 | 39.14 | 13 | RDAG-15SE2 (50) | CL211-5205-0-50 | | | | | | | | | |
| | 1.6 | | 38.38 | 47.04 | 53.04 | 25 | RDBG-25SE1 (50) | CL211-5206-3-50 | | | | | | | | | |
| YES | 1.2 | | 30.30 | 47.04 | 33.04 | 20 | RDBG-25SE2 (50) | CL211-5207-6-50 | | | | | | | | | |
| 1123 | 1.6 | | 16.34 | 24.99 | 30.81 | 9 | RDEG1-9SE1 (50) | CL211-5250-5-50 | | | | | | | | | |
| | 1.2 | | 4.99 10.54 | 24.99 | 30.61 24.98 | 9 | RDEG1-9SE2 (50) | CL211-5251-8-50 | | | | | | | | | |
| | 1.6 | 2.8 | 24.66 | 33.32 | 39.14 | 15 | RDAG1-15SE1 (50) | CL211-5254-6-50 | | | | | | | | | |
| | 1.2 | 2.0 | 24.00 | 33.32 | 35.14 | 15 | 13 | RDAG1-15SE2 (50) | CL211-5255-9-50 | | | | | | | | |
| | 1.6 | | 38.38 | 4 47.04 | 53.04 | 25 | RDBG1-25SE1 (50) | CL211-5256-1-50 | | | | | | | | | |
| | 1.2 | | 30.30 | 47.04 | 33.04 | 33.04 | 33.04 | 33.04 | 33.04 | 33.04 | 55.04 | 55.04 | 33.04 | 33.04 | 20 | RDBG1-25SE2 (50) | CL211-5257-4-50 |

Locking Screw

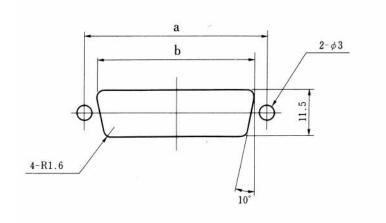


| HRS No | Part No. | Female thread size | No. of washers | Applicable panel thickness | Packaging unit (per bag) | RoHS |
|-----------------|------------------------|--------------------|----------------|-------------------------------|-----------------------------|------|
| CL211-5180-1-01 | RDG-LNA (01) | | 0 | 1.6~2.0 | | |
| CL211-5181-4-01 | RDG-LNA-W1 (01) | M2.6 × 0.45 | 1 | 0.8~1.2 | 100pieces | |
| CL211-5182-7-01 | RDG-LNA-W2 (01) | | 2 | 0~0.4 | ı | YES |
| CL211-5183-0-01 | RDG-LNA (4-40) (01) | | 0 | 1.6~2.0 | | IES |
| CL211-5184-2-01 | RDG-LNA (4-40)-W1 (01) | No.4-40UNC | 1 | 0.8~1.2 | 100pieces | |
| CL211-5185-5-01 | RDG-LNA (4-40)-W2 (01) | | 2 | 0~0.4 | | |

*All models are nickel-plated

Panel Mounting Dimensions

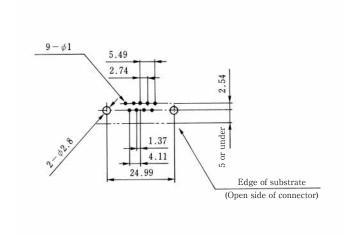
For hexagon locking screws



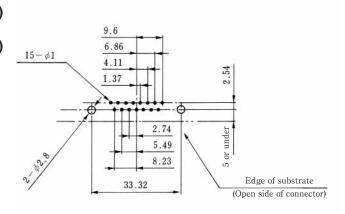
| | L | nit: mm |
|------------|-------|---------|
| Shell Size | a | b |
| Е | 24.99 | 20.2 |
| A | 33.32 | 28.6 |
| В | 47.04 | 42.3 |

PC Board Layout (mm)

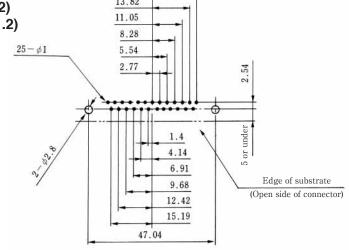
- RDEG-9SE1 (50) (Substrate thickness t=1.6)
- RDEG1-9SE1 (50) (Substrate thickness t=1.6)
- RDEG-9SE2 (50) (Substrate thickness t=1.2)
- RDEG1-9SE2 (50) (Substrate thickness t=1.2)



- RDEG-15SE1 (50) (Substrate thickness t=1.6)
- RDEG1-15SE1 (50) (Substrate thickness t=1.6)
- RDEG-15SE2 (50) (Substrate thickness t=1.2)
- RDEG1-15SE2 (50) (Substrate thickness t=1.2)



- RDEG-25SE1 (50) (Substrate thickness t=1.6)
- RDEG1-25SE1 (50) (Substrate thickness t=1.6)
- RDEG-25SE2 (50) (Substrate thickness t=1.2)
- RDEG1-25SE2 (50) (Substrate thickness t=1.2)



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